



Patent
Case No.: 53434US009

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

First Named Inventor: HOGERTON, PETER B.
Application No.: 09/690,600 Group Art Unit: 2827
Filed: October 17, 2000 Examiner: Luan C. Thai
Title: SOLVENT ASSISTED BURNISHING OF PRE-UNDERFILLED
SOLDER-BUMPED WAFERS FOR FLIPCHIP BONDING

NOTICE OF APPEAL PURSUANT TO 37 CFR § 1.191

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

CERTIFICATE OF MAILING	
I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on:	
<u>JUL 23 2004</u>	<u>Kathleen M. Murray</u>
Date	Signed by: Kathleen M. Murray

Dear Sir:

An appeal is made to the Board of Patent Appeals and Interferences from the last decision of the Examiner rejecting claims 16-19.

A Request for Extension of Time Under 37 CFR § 1.136(a) is enclosed.

Please charge the fee provided in 37 CFR § 1.17(b), and if necessary, charge any additional fees, or credit any overpayment to Deposit Account No. 13-3723. One copy of this sheet marked duplicate is also enclosed.

Respectfully submitted,

23 July 2004
Date

By: Dean M. Harts
Dean M. Harts, Reg. No.: 47,634
Telephone No.: (651) 737-2325

08/13/2004 GSTANLEY 00000000 1234567

01 FC:1401 Office of Intellectual Property Counsel
3M Innovative Properties Company
Facsimile No.: 651-736-3833